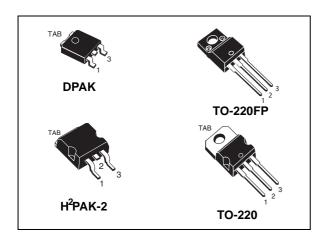
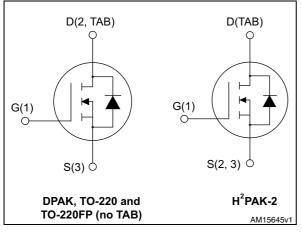
STD80N10F7, STF80N10F7, STH80N10F7-2, STP80N10F7

N-channel 100 V, 0.008 Ω typ., 80 A STripFET[™] VII DeepGATE[™] Power MOSFETs in DPAK, TO-220FP, H²PAK-2 and TO-220



life.augmented

Figure 1. Internal schematic diagram



Features

Order codes	V _{DS} @ T _{Jmax}	R _{DS(on)} max	I _D	P _{TOT}
STD80N10F7		0.01 Ω	70 A	85 W
STF80N10F7	100 V	0.01 Ω	40 A	30 W
STH80N10F7-2	100 V	0.0095 Ω	80 A	110 W
STP80N10F7	1	0.01 Ω	00 A	110 W

Datasheet - production data

- Extremely low gate charge
- Ultra low on-resistance
- Low gate input resistance

Applications

Switching applications

Description

These devices utilize the 7th generation of design rules of ST's proprietary STripFETTM technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest R_{DS(on)} in all packages.

Table 1. Device summary

		-	
Order codes	Marking	Package	Packaging
STD80N10F7		DPAK	Tape and reel
STF80N10F7	0014057	TO-220FP	Tube
STH80N10F7-2	80N10F7	H ² PAK-2	Tape and reel
STP80N10F7		TO-220	Tube

February 2014

DocID025865 Rev 1

This is information on a product in full production.

Contents

1	Electrical ratings
2	Electrical characteristics 4 2.1 Electrical characteristics (curves) 6
3	Test circuits
4	Package mechanical data 10
5	Packaging mechanical data 21
6	Revision history



1 Electrical ratings

			Value		
Symbol	Parameter	DPAK	H ² PAK-2 TO-220	TO-220FP	Unit
V _{DS}	Drain-source voltage		100		V
V _{GS}	Gate-source voltage		± 20		V
۱ _D	Drain current (continuous) at $T_C = 25 \ ^{\circ}C$	70	80	40	А
۱ _D	Drain current (continuous) at $T_C = 100 \ ^{\circ}C$	48	54	30	А
I _{DM} ⁽¹⁾	Drain current (pulsed)	280	320	160	А
P _{TOT}	Total dissipation at $T_C = 25 \ ^{\circ}C$	85	110	30	W
T _{stg}	Storage temperature		- 55 to 175		°C
Тj	Max. operating junction temperature		- 55 10 175		0

Table 2. Absolute maximum ratings

1. Pulse width limited by safe operating area.

Table 3. Thermal data

Symbol	Parameter		Unit			
Symbol	Falametei	DPAK	TO-220FP	H ² PAK-2	TO-220	
R _{thj-pcb}	Thermal resistance junction-pcb max	50		35		°C/W
R _{thj-amb}	Thermal resistance junction-ambient max		62.5		62.5	°C/W
R _{thj-case}	Thermal resistance junction-case max	1.76	5	1.3	6	°C/W



2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_{\rm D} = 250 \ \mu {\rm A}, \ {\rm V}_{\rm GS} = 0$	100			V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = 100 V V _{DS} = 100 V, T _C =125 °C			1 100	μΑ μΑ
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = 20 V			100	μA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5	3.5	4.5	V
R _{DS(on)}	Static drain-source on-resistance	for DPAK, TO-220 and TO-220FP: I _D = 40 A, V _{GS} =10 V		0.0085	0.010	Ω
	OIFIESISIANCE	for H ² PAK-2: V _{GS} =10 V, I _D =40 A		0.008	0.0095	Ω

	Table	4.	On	/off	states
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Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance		-	3100	-	pF
C _{oss}	Output capacitance	V _{DS} = 50 V, f = 1 MHz,	-	700	-	pF
C _{rss}	Reverse transfer capacitance	V _{GS} = 0	-	45	-	pF
Qg	Total gate charge	V _{DD} = 50 V, I _D = 80 A,	-	45	-	nC
Q _{gs}	Gate-source charge	V _{GS} = 10 V	-	18	-	nC
Q _{gd}	Gate-drain charge	(see Figure 18)	-	13	-	nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _d (on)	Turn-on delay time		-	19	-	ns
t _r	Rise time	V _{DD} = 50 V, I _D = 40 A, R _G = 4.7 Ω, V _{GS} = 10 V	-	32	-	ns
t _d (off)	Turn-off delay time	(see Figure 19 and Figure 22)	-	36	-	ns
t _f	Fall time		-	13	-	ns



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		80	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		320	Α
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 80 A, V _{GS} = 0	-		1.1	V
t _{rr}	Reverse recovery time	I _{SD} = 80 A, di/dt = 100 A/µs	-	70		ns
Q _{rr}	Reverse recovery charge	V _{DD} = 80 V, T _j =150 °C	-	125		nC
I _{RRM}	Reverse recovery current	(see Figure 22)	-	3.6		Α

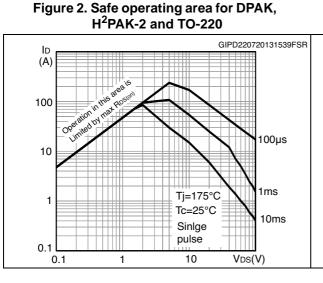
Table 7. Source drain diode

1. Pulse width limited by safe operating area.

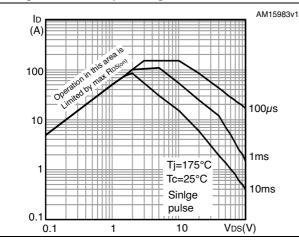
2. Pulsed: pulse duration = 300 μ s, duty cycle 1.5%



2.1 Electrical characteristics (curves)







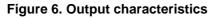
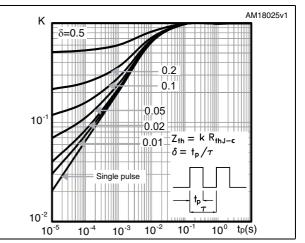
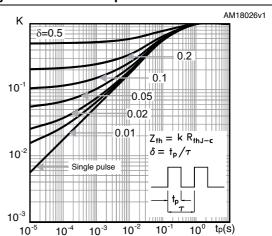


Figure 3. Thermal impedance for DPAK, H²PAK-2 and TO-220









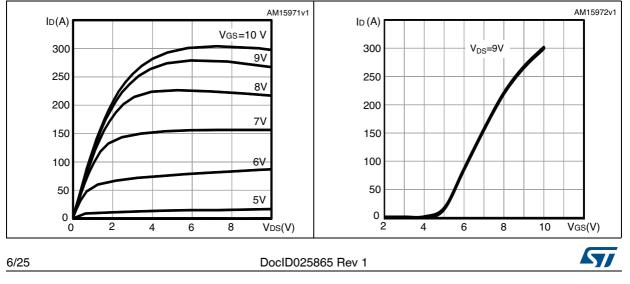
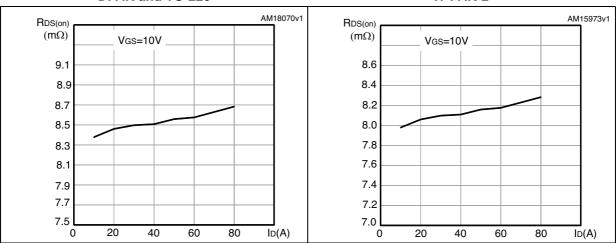


Figure 8. Static drain-source on-resistance for DPAK and TO-220







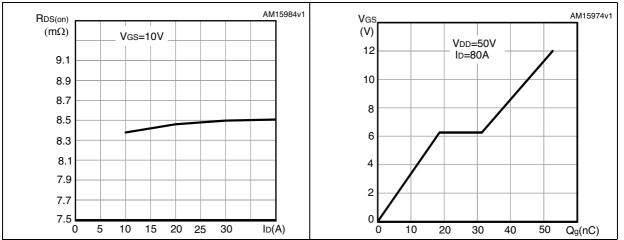




Figure 12. Capacitance variations

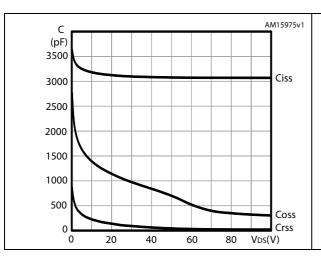
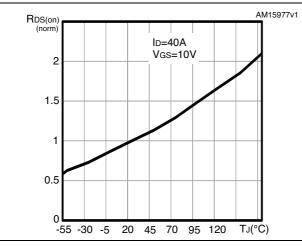
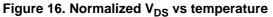
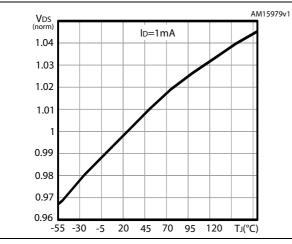


Figure 14. Normalized on-resistance vs temperature







8/25

Figure 13. Normalized gate threshold voltage vs temperature

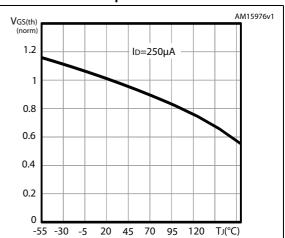
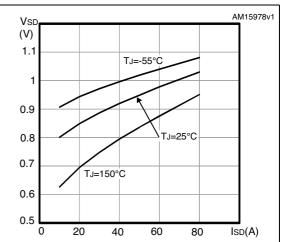


Figure 15. Source-drain diode forward characteristics





Test circuits 3

Figure 17. Switching times test circuit for resistive load

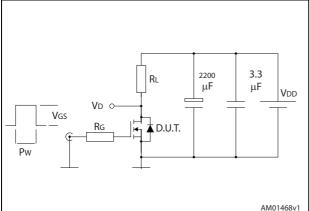


Figure 19. Test circuit for inductive load switching and diode recovery times

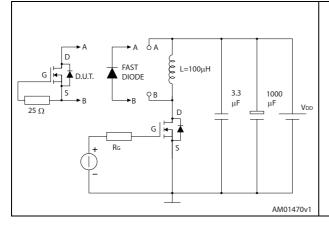
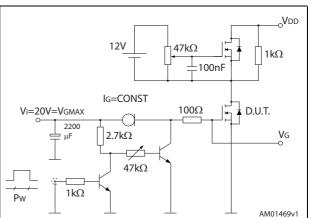
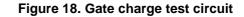
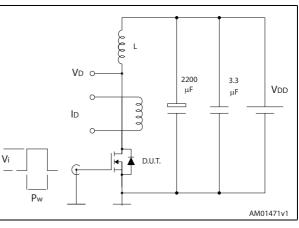


Figure 21. Unclamped inductive waveform









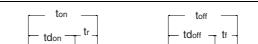
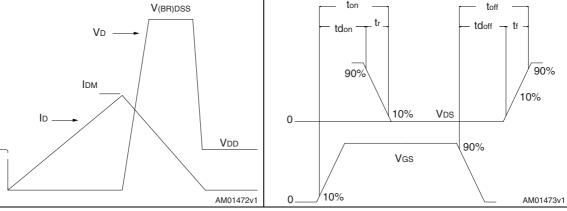


Figure 22. Switching time waveform





Vdd

4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.



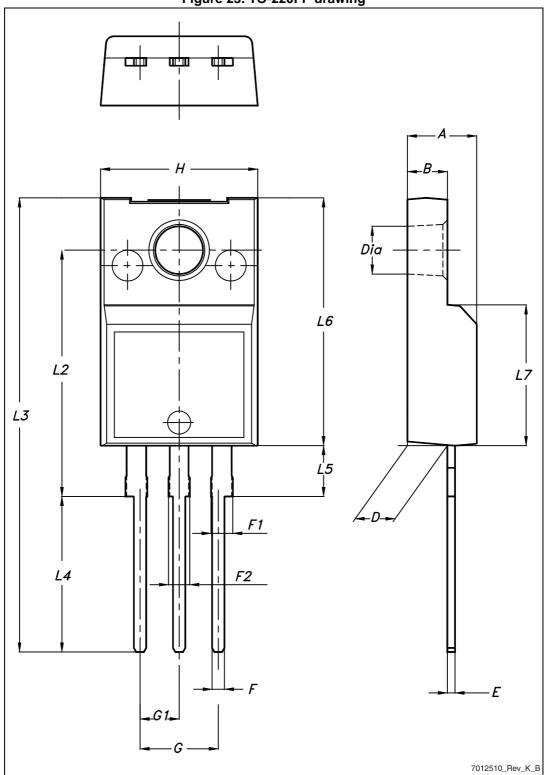


Figure 23. TO-220FP drawing



Dim.		mm				
	Min.	Тур.	Max.			
А	4.4		4.6			
В	2.5		2.7			
D	2.5		2.75			
E	0.45		0.7			
F	0.75		1			
F1	1.15		1.70			
F2	1.15		1.70			
G	4.95		5.2			
G1	2.4		2.7			
Н	10		10.4			
L2		16				
L3	28.6		30.6			
L4	9.8		10.6			
L5	2.9		3.6			
L6	15.9		16.4			
L7	9		9.3			
Dia	3		3.2			

Table 8. TO-220FP mechanical data



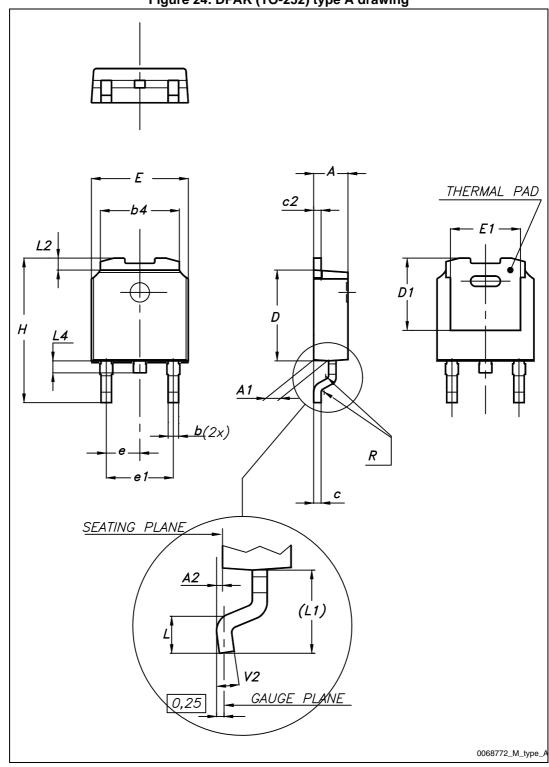


Figure 24. DPAK (TO-252) type A drawing



Dim	mm				
Dim.	Min.	Тур.	Max.		
А	2.20		2.40		
A1	0.90		1.10		
A2	0.03		0.23		
b	0.64		0.90		
b4	5.20		5.40		
С	0.45		0.60		
c2	0.48		0.60		
D	6.00		6.20		
D1		5.10			
E	6.40		6.60		
E1		4.70			
е		2.28			
e1	4.40		4.60		
Н	9.35		10.10		
L	1.00		1.50		
(L1)		2.80			
L2		0.80			
L4	0.60		1.00		
R		0.20			
V2	0°		8°		

Table 9. DPAK (TO-252) type A mechanical data



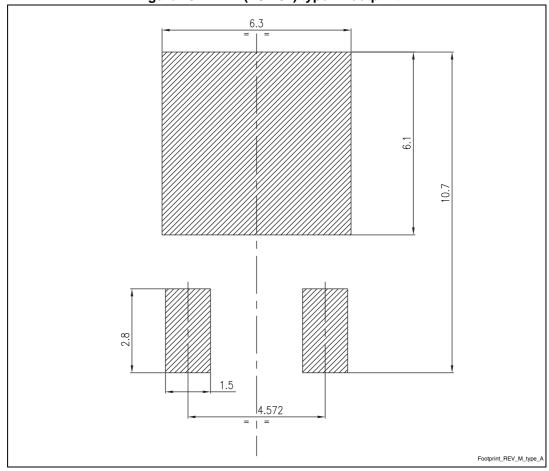
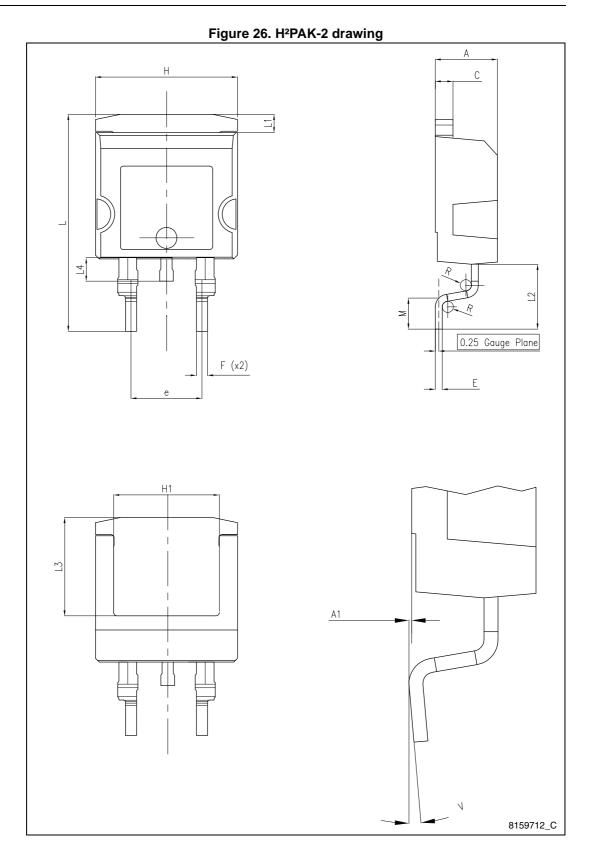


Figure 25. DPAK (TO-252) type A footprint ^(a)

a. All dimensions are in millimeters







Dim	mm				
Dim.	Min.	Тур.	Max.		
А	4.30		4.80		
A1	0.03		0.20		
С	1.17		1.37		
е	4.98		5.18		
E	0.50		0.90		
F	0.78		0.85		
Н	10.00		10.40		
H1	7.40		7.80		
L	15.30	-	15.80		
L1	1.27		1.40		
L2	4.93		5.23		
L3	6.85		7.25		
L4	1.5		1.7		
М	2.6		2.9		
R	0.20		0.60		
V	0°		8°		

Table 10. H²PAK-2 mechanical data



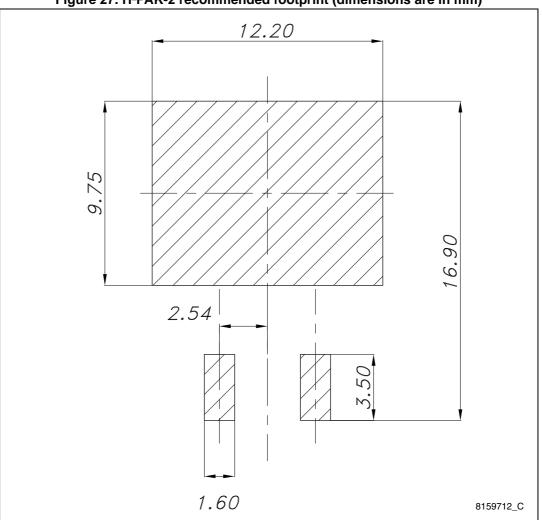


Figure 27. H²PAK-2 recommended footprint (dimensions are in mm)

18/25



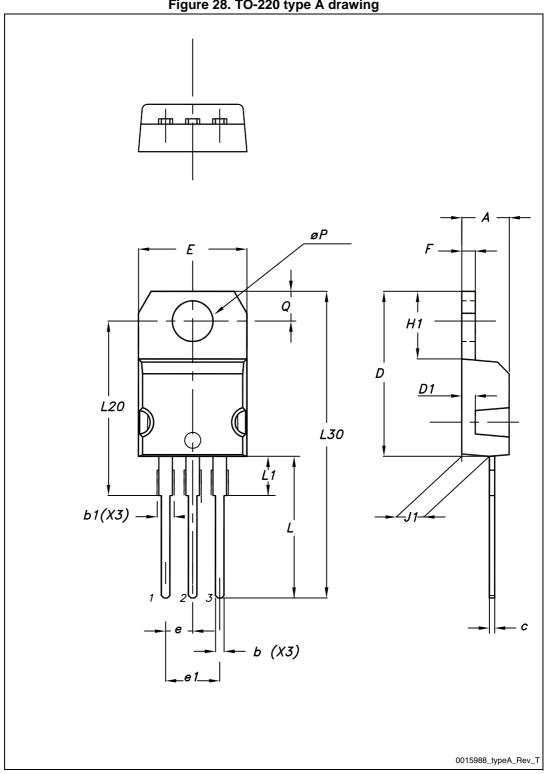


Figure 28. TO-220 type A drawing



	mm				
Dim. —	Min.	Тур.	Max.		
A	4.40		4.60		
b	0.61		0.88		
b1	1.14		1.70		
с	0.48		0.70		
D	15.25		15.75		
D1		1.27			
E	10		10.40		
е	2.40		2.70		
e1	4.95		5.15		
F	1.23		1.32		
H1	6.20		6.60		
J1	2.40		2.72		
L	13		14		
L1	3.50		3.93		
L20		16.40			
L30		28.90			
ØР	3.75		3.85		
Q	2.65		2.95		

Table 11. TO-220 type A mechanical data



5 Packaging mechanical data

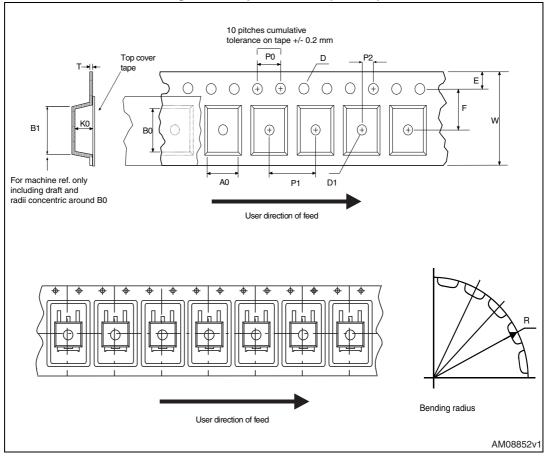


Figure 29. Tape for DPAK (TO-252)



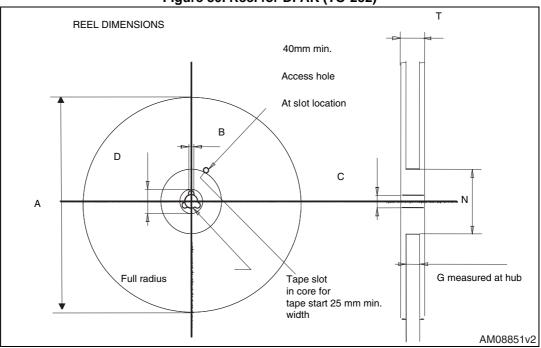


Figure 30. Reel for DPAK (TO-252)

Таре				Reel		
Dim.	mm		Dim	mm		
	Min.	Max.	— Dim.	Min.	Max.	
A0	6.8	7	А		330	
B0	10.4	10.6	В	1.5		
B1		12.1	С	12.8	13.2	
D	1.5	1.6	D	20.2		
D1	1.5		G	16.4	18.4	
E	1.65	1.85	N	50		
F	7.4	7.6	Т		22.4	
K0	2.55	2.75				
P0	3.9	4.1		Base qty.	2500	
P1	7.9	8.1		Bulk qty.	2500	
P2	1.9	2.1				
R	40					
Т	0.25	0.35				
W	15.7	16.3				

Table 12. DPAK (TO-252) tape and reel mechanical data



Таре				Reel		
Dim. –	mm		Dim	mm		
	Min.	Max.	— Dim.	Min.	Max.	
A0	10.5	10.7	Α		330	
B0	15.7	15.9	В	1.5		
D	1.5	1.6	С	12.8	13.2	
D1	1.59	1.61	D	20.2		
Е	1.65	1.85	G	24.4	26.4	
F	11.4	11.6	N	100		
K0	4.8	5.0	Т		30.4	
P0	3.9	4.1			·	
P1	11.9	12.1		Base qty 1000		
P2	1.9	2.1		Bulk qty	1000	
R	50					
Т	0.25	0.35				
W	23.7	24.3				

Table 13. H²PAK-2 tape and reel mechanical data



6 Revision history

Table 14. Do	ocument	revision	historv
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Date	Revision	Changes
07-Feb-2014	1	First release.



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